LDO Regulator – High Performance CMOS, Enable, Enhanced ESD

300 mA

NCV8603

The NCV8603 provides 300 mA of output current at fixed voltage options. It is designed for portable battery powered applications and offers high performance features such as low power operation, fast enable response time, and low dropout.

The device is designed to be used with low cost ceramic capacitors and is packaged in the TSOP-5.

Features

- Fast Enable Turn-on Time of 15 μs
- Wide Supply Voltage Range Operating Range
- Excellent Line and Load Regulation
- Typical Noise Voltage of 50 μV_{rms} without a Bypass Capacitor
- Enhanced ESD Protection (HBM 3.5 kV, MM 200 V)
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices

Typical Applications

- SMPS Post-Regulation
- Hand-held Instrumentation & Audio Players
- Noise Sensitive Circuits – VCO, RF Stages, etc.
- Camcorders and Cameras
- Portable Computing

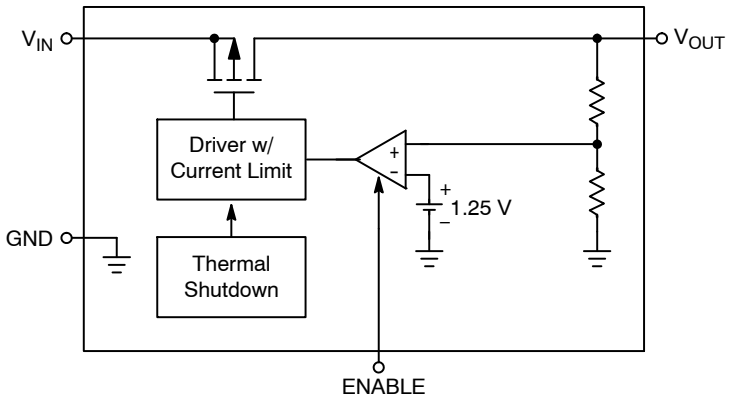
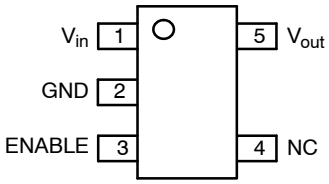


Figure 1. Simplified Block Diagram

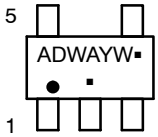
TSOP-5
SN SUFFIX
CASE 483

PIN CONNECTIONS



(Top View)

MARKING DIAGRAM



ADW	= Specific Device Code
A	= Assembly Location
Y	= Year
W	= Work Week
▪	= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

PIN FUNCTION DESCRIPTION

Pin No.	Pin Name	Description
1	V_{in}	Positive Power Supply Input
2	GND	Power Supply Ground; Device Substrate
3	ENABLE	The Enable Input places the device into low-power standby when pulled to logic low (< 0.4 V). Connect to V_{in} if the function is not used.
4	NC	No Connection (Note 1)
5	V_{out}	Regulated Output Voltage

1. True no connect. Printed circuit board traces are allowable.

ABSOLUTE MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V_{in}	Input Voltage (Note 2)	−0.3 to 6.5	V
V_{out}, ENABLE	Output, Enable	−0.3 to 6.5 (or V_{in} + 0.3) Whichever is Lower	V
$T_{J(max)}$	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature	−65 to 150	°C
ESD_{HBM}	ESD Capability, Human Body Model (Note 3)	3500	V
ESD_{MM}	ESD Capability, Machine Model (Note 3)	200	V
MSL	Moisture Sensitivity Level	MSL1/260	–

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
3. This device series incorporates ESD protection and is tested by the following methods:
   ESD Human Body Model tested per AEC−Q100−002 (EIA/JESD22−A114)
   ESD Machine Model tested per AEC−Q100−003 (EIA/JESD22−A115)
   Latchup Current Maximum Rating: ≤150 mA per JEDEC standard: JESD78.

THERMAL CHARACTERISTICS

Symbol	Rating	Value	Unit
$R_{\theta JA}$	Thermal Characteristics, TSOP-5 (Note 4) Thermal Resistance, Junction-to-Air (Note 5)	215	°C/W

4. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
5. Value based on copper area of 645 mm^2 (or 1 in^2) of 1 oz copper thickness.

OPERATING RANGES (Note 6)

Symbol	Rating	Min	Max	Unit
V_{in}	Input Voltage (Note 7)	1.75	6	V
I_{out}	Output Current	0	300	mA
T_A	Ambient Temperature	−40	125	°C

6. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
7. Minimum V_{in} = 1.75 V or (V_{out} + V_{DO}), whichever is higher.

ELECTRICAL CHARACTERISTICS

(V_{in} = V_{out} + 0.5 V (fixed version), C_{in} = C_{out} =1.0 μF, for typical values T_A = 25°C, for min/max values T_A = −40°C to 125°C, unless otherwise specified.) (Note 8)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
Regulator Output						
V_{out}	Output Voltage	I_{out} = 1.0 mA to 300 mA V_{in} = (V_{out} + 0.5 V) to 6.0 V	(−3%) 3.201	3.3	(+3%) 3.399	V
PSRR	Power Supply Ripple Rejection (Note 9)	I_{out} = 1.0 mA to 150 mA V_{in} = V_{out} + 1 V + 0.5 V_{p-p} f = 120 Hz f = 1.0 kHz f = 10 kHz	 – – –	 62 55 38	 – – –	dB
Reg_{line}	Line Regulation	V_{in} = 1.750 V to 6.0 V, I_{out} = 1.0 mA	–	1.0	10	mV
Reg_{load}	Load Regulation	I_{out} = 1.0 mA to 300 mA	–	2.0	45	mV
V_n	Output Noise Voltage (Note 9)	f = 10 Hz to 100 kHz	–	50	–	μV_{rms}
I_{sc}	Output Short Circuit Current		350	650	900	mA
V_{DO}	Dropout Voltage	Measured at: V_{out} − 2.0% I_{out} = 300 mA	–	157	230	mV
$I_{out(max)}$	Output Current Limit (Note 9)		300	650	–	mA
General	**General**					
I_{DIS}	Disable Current	ENABLE = 0 V, Vin = 6 V −40°C ≤ T_A ≤ 85°C	–	0.01	1.0	μA
I_{GND}	Ground Current	ENABLE = 0.9 V, I_{out} = 1.0 mA to 300 mA	–	145	180	μA
T_{SD}	Thermal Shutdown Temperature (Note 9)		–	175	–	°C
T_{SH}	Thermal Shutdown Hysteresis (Note 9)		–	10	–	°C
Chip Enable						
$V_{th(EN)}$	ENABLE Input Threshold Voltage Voltage Increasing, Logic High Voltage Decreasing, Logic Low		 0.9 –	 – –	 – 0.4	V
I_{EN}	Enable Input Bias Current (Note 9)		–	3.0	100	nA
Timing	**Timing**					
t_{EN}	Output Turn On Time (Note 9)	ENABLE = 0 V to V_{in}	–	15	25	μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

8. Performance guaranteed over the indicated operating temperature range by design and/or characterization, production tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
9. Values based on design and/or characterization.

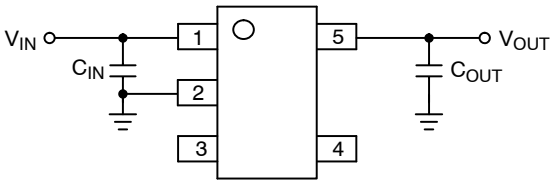


Figure 2. Typical Application Circuit

TYPICAL CHARACTERISTICS

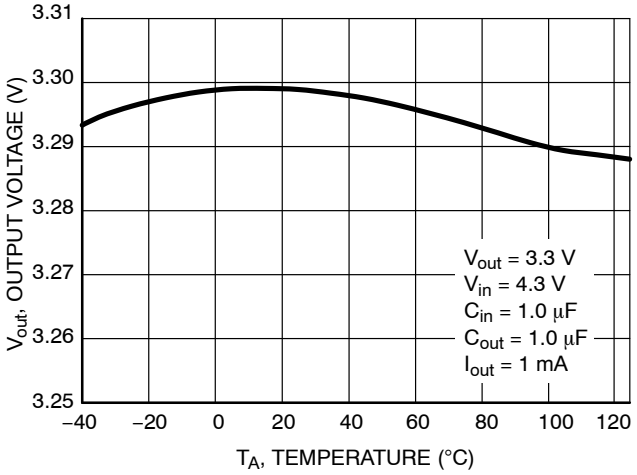


Figure 3. V_{out} vs. Temperature

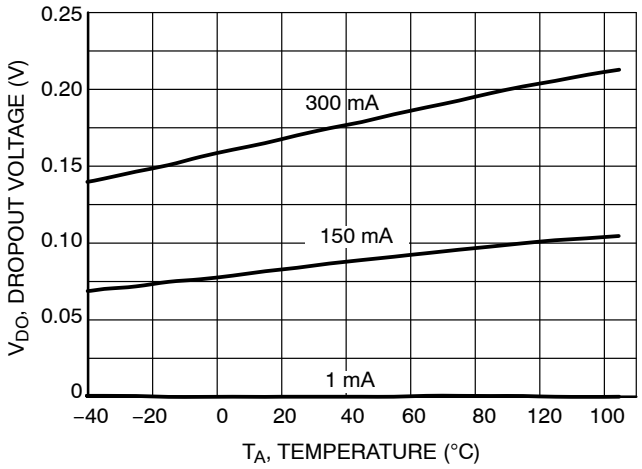


Figure 4. Dropout Voltage vs. Temperature (Over Current Range)

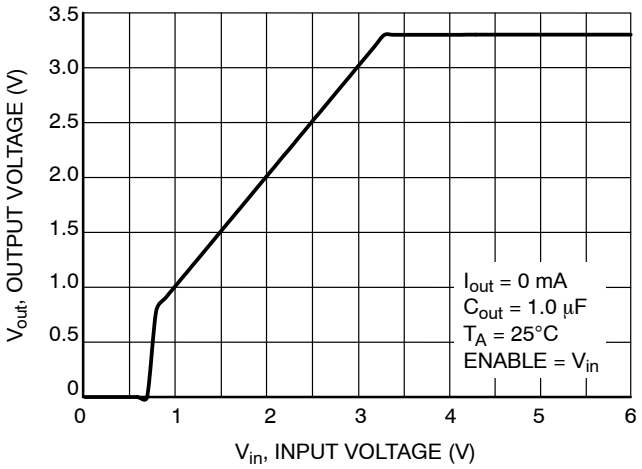


Figure 5. Output Voltage vs. Input Voltage

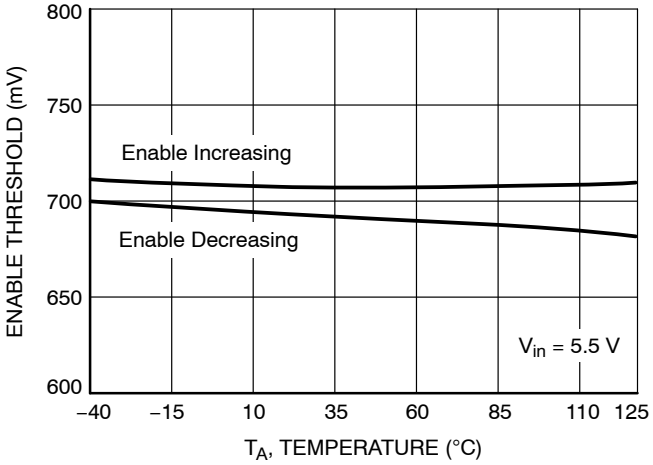


Figure 6. Enable Threshold vs. Temperature

TYPICAL CHARACTERISTICS (continued)

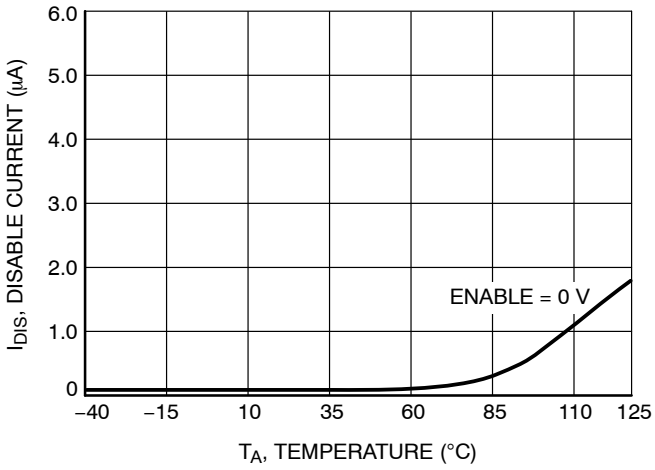


Figure 7. Ground Current (Sleep Mode) vs. Temperature

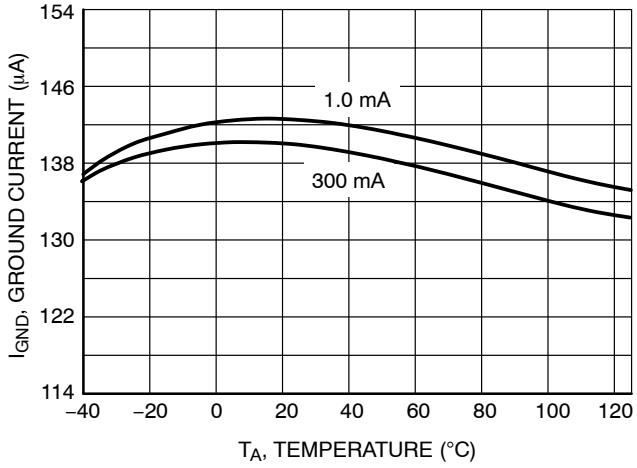


Figure 8. Ground Current vs. Temperature

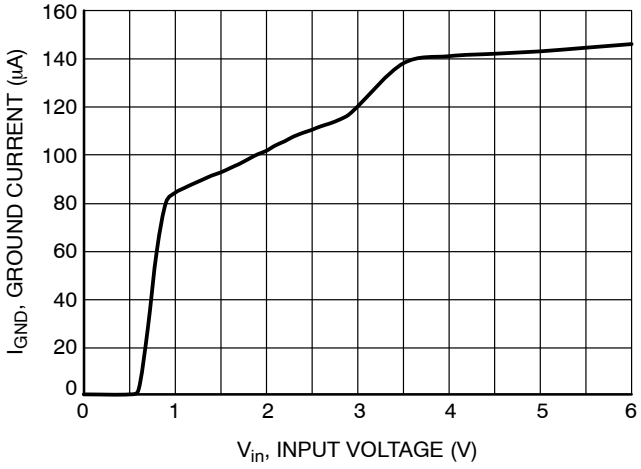


Figure 9. Ground Current vs. Input Voltage

TYPICAL CHARACTERISTICS (continued)

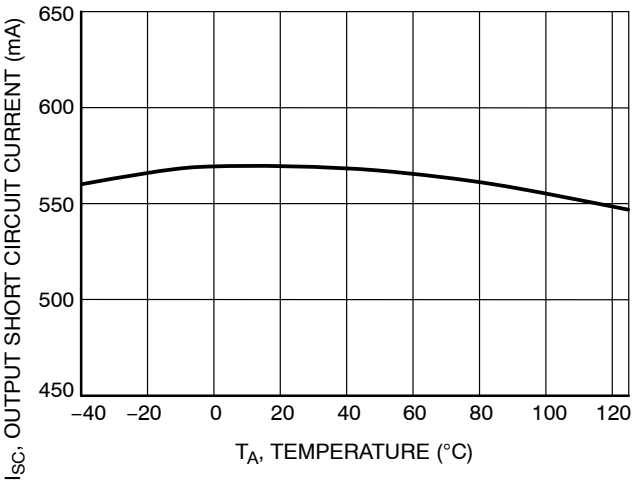


Figure 10. Output Short Circuit Current vs. Temperature

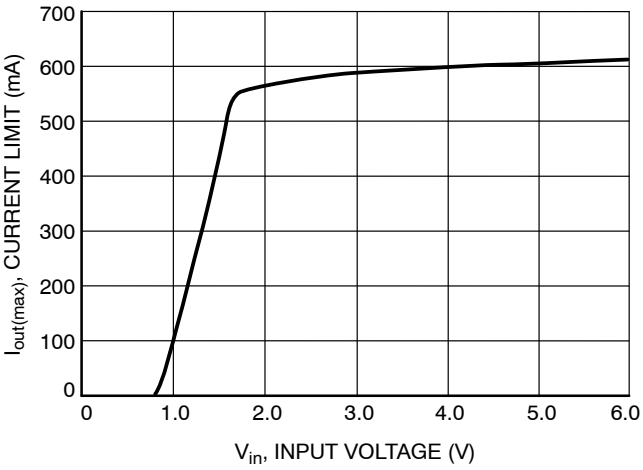


Figure 11. Current Limit vs. Input Voltage

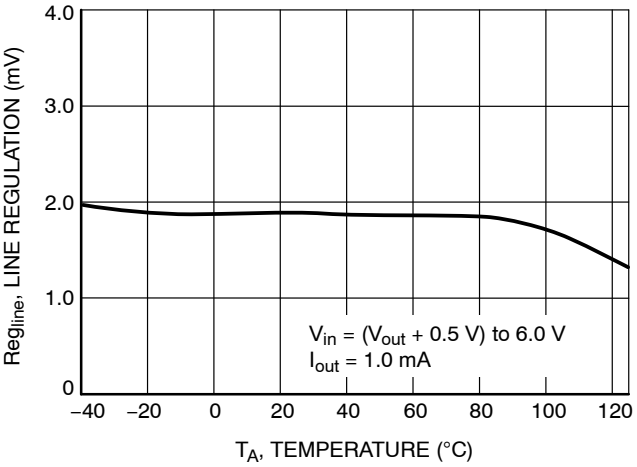


Figure 12. Line Regulation vs. Temperature

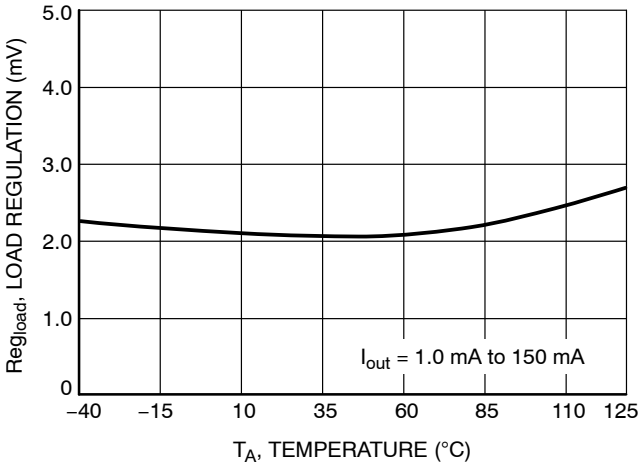


Figure 13. Load Regulation vs. Temperature

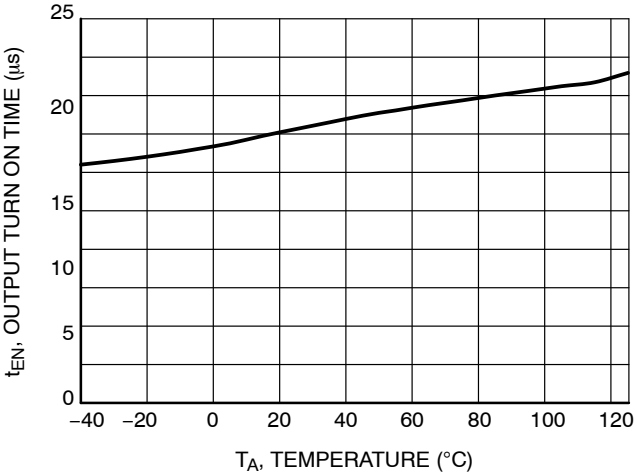


Figure 14. Output Turn On Time vs. Temperature

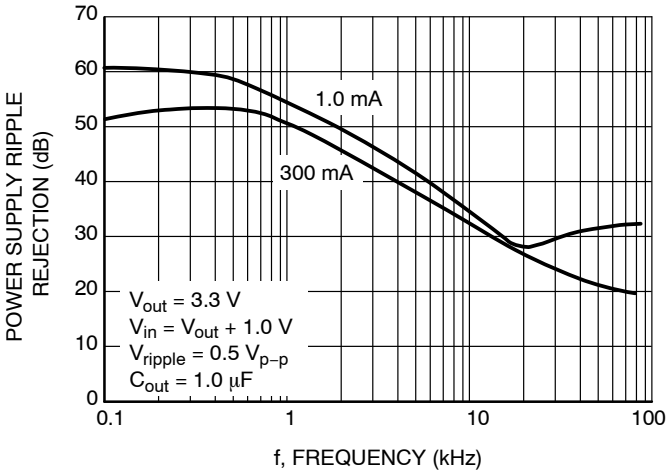


Figure 15. Power Supply Ripple Rejection vs. Frequency

TYPICAL CHARACTERISTICS (continued)

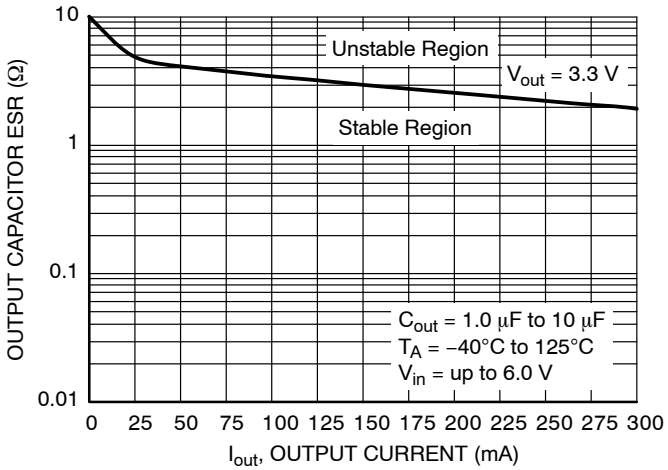


Figure 16. Output Stability with Output Capacitor ESR over Output Current

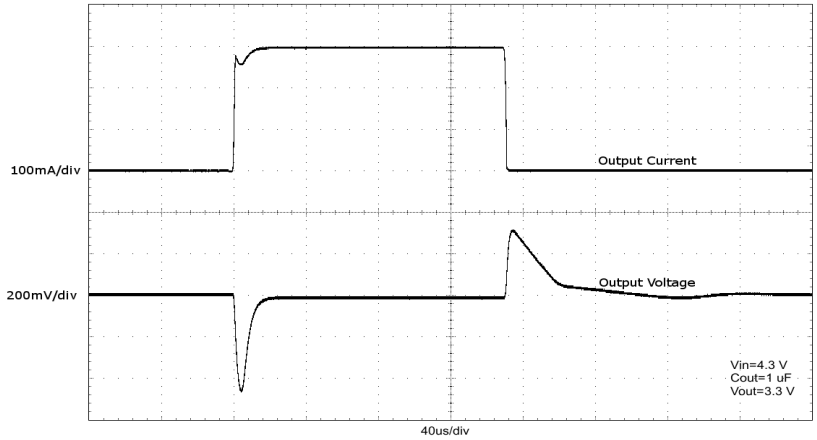


Figure 17. Load Transient Response (1.0 μF)

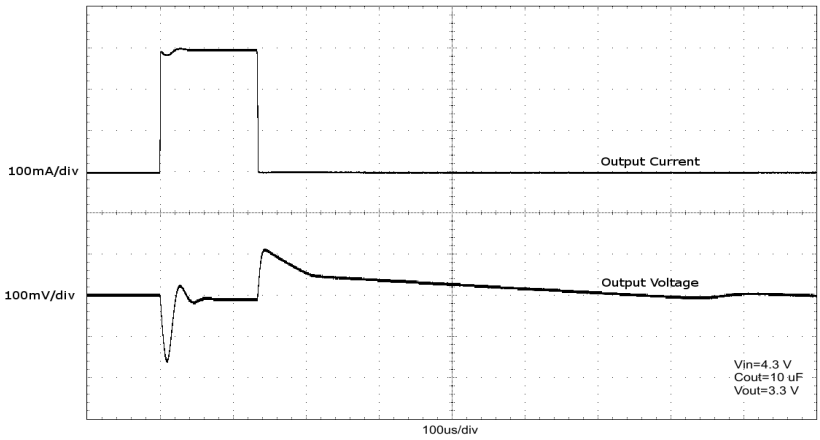


Figure 18. Load Transient Response (10 μF)

DEFINITIONS

Load Regulation

The change in output voltage for a change in output load current at a constant temperature.

Dropout Voltage

The input/output differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 2% below its nominal. The junction temperature, load current, and minimum input supply requirements affect the dropout level.

Output Noise Voltage

This is the integrated value of the output noise over a specified frequency range. Input voltage and output load current are kept constant during the measurement. Results are expressed in μV_{rms} or nV $\sqrt{}$ Hz.

Ground Current

Ground Current is the current that flows through the ground pin when the regulator operates without a load on its output (I_{GND}). This consists of internal IC operation, bias, etc. It is actually the difference between the input current (measured through the LDO input pin) and the output load current. If the regulator has an input pin that reduces its internal bias and shuts off the output (enable/disable function), this term is called the standby current (I_{STBY}.)

Line Regulation

The change in output voltage for a change in input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that the average junction temperature is not significantly affected.

Line Transient Response

Typical output voltage overshoot and undershoot response when the input voltage is excited with a given slope.

Load Transient Response

Typical output voltage overshoot and undershoot response when the output current is excited with a given slope between no-load and full-load conditions.

Thermal Protection

Internal thermal shutdown circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When activated at typically 175°C, the regulator turns off. This feature is provided to prevent failures from accidental overheating.

Maximum Package Power Dissipation

The power dissipation level at which the junction temperature reaches its maximum operating value.

APPLICATIONS INFORMATION

The NCV8603 series regulator is self-protected with internal thermal shutdown and internal current limit. Typical application circuit is shown in Figure 2.

Input Decoupling (C_{in})

A ceramic or tantalum 1.0 μF capacitor is recommended and should be connected close to the NCV8603 package. Higher capacitance and lower ESR will improve the overall line transient response.

Output Decoupling (C_{out})

The NCV8603 is a stable component and does not require a minimum Equivalent Series Resistance (ESR) for the output capacitor. The minimum output decoupling value is 1.0 μF and can be augmented to fulfill stringent load transient requirements. The regulator works with ceramic chip capacitors as well as tantalum devices. Larger values improve noise rejection and load regulation transient response. Figure 16 shows the stability region for a range of operating conditions and ESR values.

No-Load Regulation Considerations

The NCV8603 adjustable regulator will operate properly under conditions where the only load current is through the resistor divider that sets the output voltage. However, in the case where the NCV8603 is configured to provide a 1.250 V output, there is no resistor divider. If the part is enabled under no-load conditions, leakage current through the pass transistor at junction temperatures above 85°C can approach several microamperes, especially as junction temperature approaches 150°C. If this leakage current is not directed into a load, the output voltage will rise up to a level approximately 20 mV above nominal.

The NCV8603 contains an overshoot clamp circuit to improve transient response during a load current step release. When output voltage exceeds the nominal by approximately 20 mV, this circuit becomes active and clamps the output from further voltage increase. Tying the ENABLE pin to V_{in} will ensure that the part is active whenever the supply voltage is present, thus guaranteeing that the clamp circuit is active whenever leakage current is present.

When the NCV8603 adjustable regulator is disabled, the overshoot clamp circuit becomes inactive and the pass transistor leakage will charge any capacitance on V_{out}. If no load is present, the output can charge up to within a few millivolts of V_{in}. In most applications, the load will present some impedance to V_{out} such that the output voltage will be inherently clamped at a safe level. A minimum load of 10 μA is recommended.

Noise Decoupling

The NCV8603 is a low noise regulator and needs no external noise reduction capacitor. Unlike other low noise regulators which require an external capacitor and have slow startup times, the NCV8603 operates without a noise reduction capacitor, has a typical 15 μs start up delay and achieves a 50 μV_{rms} overall noise level between 10 Hz and 100 kHz.

Enable Operation

The enable pin will turn the regulator on or off. The threshold limits are covered in the electrical characteristics table in this data sheet. The turn-on/turn-off transient voltage being supplied to the enable pin should exceed a slew rate of 10 mV/μs to ensure correct operation. If the enable function is not to be used then the pin should be connected to V_{in}.

Thermal

As power in the NCV8603 increases, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and the ambient temperature affect the rate of junction temperature rise for the part. When the NCV8603 has good thermal conductivity through the PCB, the junction temperature will be relatively low with high power applications. The maximum dissipation the NCV8603 can handle is given by:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{R_{\theta JA}} \quad \text{(eq. 1)}$$

Since T_J is not recommended to exceed 125°C ($T_{J(MAX)}$), then the NCV8603 can dissipate up to 465 mW when the ambient temperature (T_A) is 25°C and the device is assembled on 1 oz PCB with 645 mm^2 area.

The power dissipated by the NCV8603 can be calculated from the following equations:

$$P_D \approx V_{IN}(I_{GND@IOUT}) + I_{OUT}(V_{IN} - V_{OUT}) \quad \text{(eq. 2)}$$

or

$$V_{IN(MAX)} \approx \frac{P_{D(MAX)} + (V_{OUT} \times I_{OUT})}{I_{OUT} + I_{GND}} \quad \text{(eq. 3)}$$

Hints

V_{in} and GND printed circuit board traces should be as wide as possible. When the impedance of these traces is high, there is a chance to pick up noise or cause the regulator to malfunction. Place external components, especially the output capacitor, as close as possible to the NCV8603, and make traces as short as possible.

DEVICE ORDERING INFORMATION

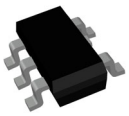
Device	Marking Code	Version	Package	Shipping†
NCV8603SN33T1G*	ADW	3.3 V	TSOP-5 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

* NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable

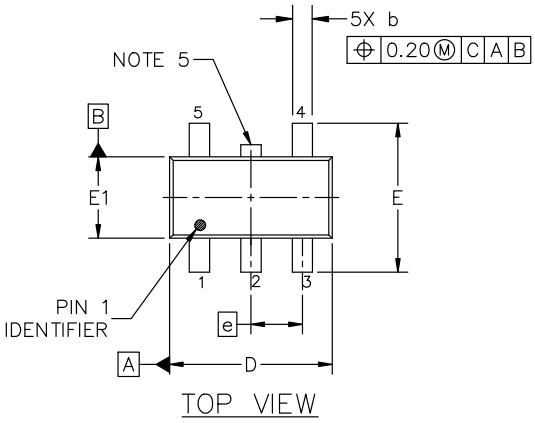
REVISION HISTORY

Revision	Description of Changes	Date
3	Rebranded the Data Sheet to **onsemi** format.	6/24/2025

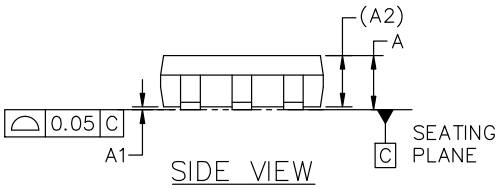


TSOP−5 3.00x1.50x0.95, 0.95P
CASE 483
ISSUE P

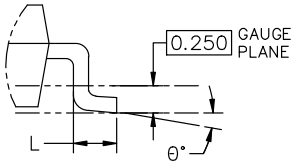
DATE 01 APR 2024



TOP VIEW



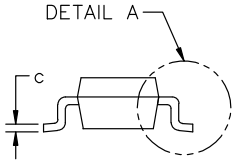
SIDE VIEW



DETAIL "A"
SCALE 2:1

NOTES:

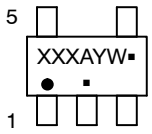
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES).
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.



END VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.900	1.000	1.100
A1	0.010	0.055	0.100
A2		0.950 REF.	
b	0.250	0.375	0.500
c	0.100	0.180	0.260
D	2.850	3.000	3.150
E	2.500	2.750	3.000
E1	1.350	1.500	1.650
e		0.950 BSC	
L	0.200	0.400	0.600
θ	0°	5°	10°

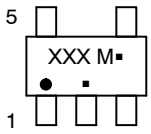
GENERIC
MARKING DIAGRAM*



Analog

XXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb−Free Package

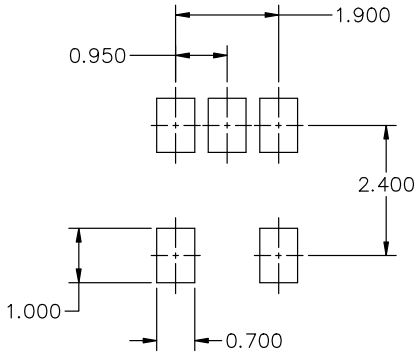
(Note: Microdot may be in either location)



Discrete/Logic

XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

DOCUMENT NUMBER:	**98ARB18753C**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**TSOP−5 3.00x1.50x0.95, 0.95P**	**PAGE 1 OF 1**

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales